

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SanDisk Corporation	04/04/2011
RECEIVING PARTY DATA	
Name:	SanDisk Technologies Inc.
Street Address:	6900 North Dallas Parkway
Internal Address:	Two Legacy Town Center
City:	Plano
State/Country:	TEXAS
Postal Code:	75024
PROPERTY NUMBERS Total: 1	
Property Type	Number
Patent Number:	7779184
CORRESPONDENCE DATA	
Fax Number:	(408)801-9019
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	4088012863
Email:	simona.benjamin@sandisk.com
Correspondent Name:	SanDisk Corporation
Address Line 1:	601 Mccarthy Boulevard
Address Line 2:	Patent Department/Simona Benjamin
Address Line 4:	Milpitas, CALIFORNIA 95035
ATTORNEY DOCKET NUMBER:	SDA-1177X-US
NAME OF SUBMITTER:	Simona Benjamin
Total Attachments: 5 source=page 13#page1.tif source=page 13#page2.tif source=page 13#page3.tif source=page 13#page4.tif source=page 13#page5.tif	

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PATENT
REEL: 026262 FRAME: 0223

ASSIGNMENT

WHEREAS, SanDisk Corporation, a Delaware corporation, doing business at 601 McCarthy Boulevard, Milpitas, CA 95035 (hereinafter referred to as **ASSIGNOR**), holds right, title and interest throughout the world in and to the patents and patent applications set forth in the attached Exhibit A, together with all divisions, continuations, or continuations-in-part thereof, and all patents issuing thereon including reissues, renewals, substitutions, re-examinations and extensions thereof, and any and all corresponding foreign patents and patent applications (hereinafter referred to as, collectively, **THE ASSIGNED PATENT RIGHTS**);

WHEREAS, SanDisk Technologies Inc., a Texas corporation, doing business at Two Legacy Town Center, 6900 North Dallas Parkway, Plano, Texas 75024, (hereinafter referred to as **ASSIGNEE**), is desirous of acquiring the full and exclusive right, title and interest in **THE ASSIGNED PATENT RIGHTS**;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, **ASSIGNOR** hereby assigns, transfers and conveys unto the said **ASSIGNEE**, and **ASSIGNEE** accepts, all of **ASSIGNOR**'s right, title and interest throughout the world in and to **THE ASSIGNED PATENT RIGHTS** and to all Letters Patent or applications or similar legal protection, not only in the United States and its territorial possessions, but in all countries foreign thereto to be obtained for **THE ASSIGNED PATENT RIGHTS**, and to any continuation, division, renewal, substitute or reissue thereof or any legal equivalent thereof in the United States or a foreign country for the full term or terms for which the same may be granted, including all priority rights under the International Convention; and **ASSIGNOR** hereby authorizes and requests the United States Commissioner of Patents and Trademarks and any officials of foreign countries whose duty it is to issue patents on applications as aforesaid, to issue all patents for **THE ASSIGNED PATENT RIGHTS** to **ASSIGNEE** in accordance with the terms of this **ASSIGNMENT** but subject to reserved rights including but not limited to those previously retained by, granted to, or owned by, the United States government, educational institutions or both and hereby transfers and conveys all rights of action, power and benefit belonging to or accruing from **THE ASSIGNED PATENT RIGHTS** including the right to undertake proceedings to recover past and future damages and claim all other relief in respect of any acts of infringement thereof whether such acts shall have been committed before or after the date of this assignment.

No other rights, immunities, or licenses, including, without limitation, any rights to any intellectual property owned, controlled or licensable by **ASSIGNOR** are granted or assigned to **ASSIGNEE** under this **ASSIGNMENT**, either expressly or by implication, estoppel, or otherwise, other than the rights expressly recited herein.

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would knowingly conflict with this Agreement;

ASSIGNOR further covenants that **ASSIGNEE** will, upon its lawful request, reasonably be provided with all pertinent facts and documents relating to **THE ASSIGNED PATENT RIGHTS** and legal equivalents as may be known and reasonably accessible to **ASSIGNOR** and that **ASSIGNOR** will testify as to the same in any administrative contest or litigation related thereto and will promptly execute and deliver to **ASSIGNEE** or its legal representative any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce **THE ASSIGNED PATENT RIGHTS** and said equivalents in the United States or in any foreign country, which may be necessary or desirable to carry out the purposes thereof.

IN TESTIMONY WHEREOF, I hereunto set my hand as of the date indicated below.

SANDISK CORPORATION

Dated: 4th April 2011

Judy Bruner
Name: Judy Bruner
Title: EVP and CFO

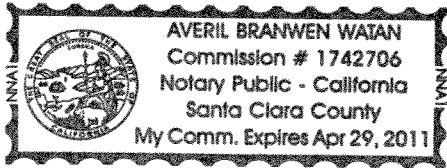
STATE OF California)
COUNTY OF Santa Clara) ss.

On this 4th day of April, 2011, before me Averil Branwen Watan (Notary Public), the undersigned Notary Public, personally appeared Judy Bruner,

who proved to me on the basis of satisfactory evidence to be the person(s) whose name(s) is/are subscribed to the within instrument and acknowledged to me that he/she/they executed the same in his/her/their authorized capacity(ies), and that by his/her/their signature(s) on the instrument the person(s), or the entity upon behalf of which the person(s) acted, executed the instrument.

I certify under PENALTY OF PERJURY under the laws of the State of California that the foregoing paragraph is true and correct.

WITNESS my hand and official seal.



Signature: Averil Branwen Watan
Signature of Notary Public

We accept the Assignment

SANDISK TECHNOLOGIES INC.

Dated: 4/4/11

James F. Brelsford
Name: James F. Brelsford
Title: President and Secretary

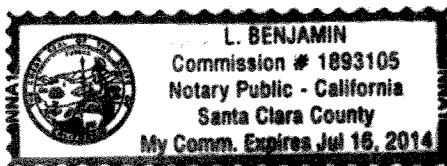
STATE OF California)
COUNTY OF Santa Clara) ss.

On this 4 day of April, 2011, before me L. Benjamin, the undersigned Notary Public, personally appeared JAMES F. BRELSFORD

who proved to me on the basis of satisfactory evidence to be the person(s) whose name(s) is/are subscribed to the within instrument and acknowledged to me that he/she/they executed the same in his/her/their authorized capacity(ies), and that by his/her/their signature(s) on the instrument the person(s), or the entity upon behalf of which the person(s) acted, executed the instrument.

I certify under PENALTY OF PERJURY under the laws of the State of California that the foregoing paragraph is true and correct.

WITNESS my hand and official seal.



Signature: L. Benjamin
Signature of Notary Public

Exhibit A

FILE #	INVENTORS	TITLE	COUNTRY	STATUS	SER #	FILING DATE	PAT #	ISSUE DATE
SDA-1167X-US	Shih-Chung Lee	Coarse/Fine Program Verification in Non-Volatile Memory Using Different Reference Levels for Improving Sensing	US	Issued	11773032	3-Jul-07	7508715	24-Mar-09
SDA-1167Y-US	Shih-Chung Lee	Systems for Coarse/Fine Program Verification in Non-Volatile Memory Using Different Reference Levels for Improving Sensing	US	Issued	11773035	3-Jul-07	7599224	6-Oct-09
SDA-1168X-I-US	Cheeman Yu, Vani Verma, Hem Takiar	Method of Fabricating a Two-Sided Die in a Four-Sided Leadframe Based Package	US	Published	12819818	21-Jun-10		
SDA-1168X-US	Cheeman Yu, Vani Verma, Hem Takiar	Method of Fabricating a Two-Sided Die in a Four-Sided Leadframe Based Package	US	Allowed	11770052	28-Jun-07		
SDA-1168Y-US	Cheeman Yu, Vani Verma, Hem Takiar	Two-Sided Die in a Four-Sided Leadframe Based Package	US	Published	11770066	28-Jun-07		
SDA-1169X-US	Chin-Tien Hope Chiu, Hem Takiar, Chih Chin Liao, Cheeman Yu, Ning Ye, Jack Chang Chien	Method of Fabricating a Semiconductor Package having Through Holes for Molding Back Side of Package	US	Allowed	11770078	28-Jun-07		
SDA-1169Y-US	Chin-Tien Hope Chiu, Hem Takiar, Chih Chin Liao, Cheeman Yu, Ning Ye, Jack Chang Chien	Semiconductor Package having Through Holes for Molding Back Side of Package	US	Published	11770088	28-Jun-07		
SDA-1170X-US	Andrew (Chien-Ko) Liao, Chin-Tien Hope Chiu, Jack Chang Chien, Cheeman Yu, Hem Takiar	Method of Fabricating a Semiconductor Die Having a Redistribution Layer	US	Issued	11769927	28-Jun-07	7772047	10-Aug-10
SDA-1170Y-I-US	Andrew (Chien-Ko) Liao, Chin-Tien Hope Chiu, Jack Chang Chien, Cheeman Yu, Hem Takiar	Semiconductor Die Having a Redistribution Layer	US	Allowed	12843279	26-Jul-10		
SDA-1170Y-US	Andrew (Chien-Ko) Liao, Chin-Tien Hope Chiu, Jack Chang Chien, Cheeman Yu, Hem Takiar	Semiconductor Die Having a Redistribution Layer	US	Issued	11769937	28-Jun-07	7763980	27-Jul-10
SDA-1171X-US	Ning Ye, Robert C Miller, Cheeman Yu, Hem Takiar, Andre McKenzie	Method of Fabricating a Memory Card Using SIP/SMT Hybrid Technology	US	Published	11769942	28-Jun-07		
SDA-1171Y-US	Ning Ye, Robert C Miller, Cheeman Yu, Hem Takiar, Andre McKenzie	Memory Card Fabricated Using SIP/SMT Hybrid Technology	US	Issued	11769954	28-Jun-07	7772686	10-Aug-10
SDA-1174X-US	Jonathan Hubert, Jason Patrick Hanlon, Jordan MacDonald	Method of Adapting an Expresscard Slot for Smaller Form Factor Memory Compatibility	US	Published	11771763	29-Jun-07		
SDA-1174Y-US	Jonathan Hubert, Jason Patrick Hanlon, Jordan MacDonald	Adaptor for an Expresscard Slot	US	Issued	11771767	29-Jun-07	7699660	20-Apr-10
SDA-1175Y-I-US	Jonathan Hubert, Jason Patrick Hanlon, Jordan MacDonald, Wesley G. Brewer	Memory Card for an Expresscard Slot	US	Published	12727519	19-Mar-10		
SDA-1175Y-US	Jonathan Hubert, Jason Patrick Hanlon, Jordan MacDonald, Wesley G. Brewer	Memory Card for an Expresscard Slot	US	Issued	11771756	29-Jun-07	7686654	30-Mar-10
SDA-1176Y-US	Jonathan Hubert, Jason Patrick Hanlon, Matthijs Hutten	Adapter System for Use with ExpressCard Slot	US	Issued	11771730	29-Jun-07	7780477	24-Aug-10
SDA-1177X-US	Jonathan Hubert, Jason Patrick Hanlon	Method of Using the Dual Bus Interface in an ExpressCard Slot	US	Issued	11771744	29-Jun-07	7779184	17-Aug-10
SDA-1177Y-US	Jonathan Hubert, Jason Patrick Hanlon	Dual Bus ExpressCard Peripheral Device	US	Published	11771752	29-Jun-07		
SDA-1178-1X-US	Gerrit Jan Hemink, Teruhiko Kamei	Erase Voltage Manipulation in Non-Volatile Memory for Controlled Shifts in Threshold Voltage	US	Issued	11773921	5-Jul-07	7457166	25-Nov-08